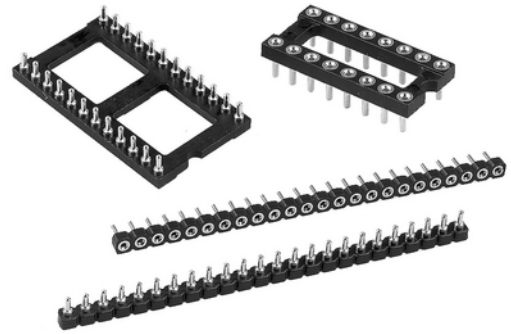


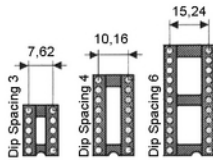
### Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial	Hülse: Messing gedreht Feder: 4-Lamellen-Clip, Beryllium-Kupfer <i>Sleeve: screw machined brass</i> <i>Clip: 4-Finger-Clip, Beryllium-Copper</i>
Contact Material	
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni (2 ... 3µm) <i>Acc. to options (see below), over Ni (2 ... 3µm)</i>
Lötbarkeit	IEC 60512-12A
Solderability	IEC 60512-12A
Durchgangswiderstand <i>Contact Resistance</i>	< 10mΩ
Contact Resistance	< 10mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000MΩ
Insulation Resistance	> 1000MΩ
Spannungsfestigkeit <i>Test Voltage</i>	1kV <sub>RMS</sub>
Test Voltage	1kV <sub>RMS</sub>
Nennspannung <i>Voltage Rating</i>	100V <sub>RMS</sub> / 150V <sub>DC</sub>
Voltage Rating	100V <sub>RMS</sub> / 150V <sub>DC</sub>
Nennstrom	3A
Current Rating	3A
Temperaturbereich <i>Temperature Range</i>	-55°C ... +125°C
Temperature Range	-55°C ... +125°C
Verarbeitung <i>Processing</i>	Wellen- oder Reflow-Lötverfahren <i>Wave or reflow soldering</i>

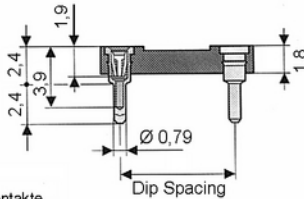


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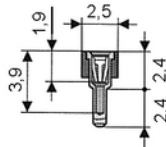
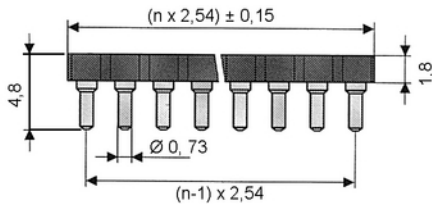
Für Rundstifte Ø0,40-0,56mm  
oder Vierkantstifte 0,25x0,45mm.  
For Ø0.40-0.56mm round pins  
or 0.25x0.45mm rectangular pins.



n = Anzahl Kontakte  
n = No. of Contacts



IC-Fassung Serie 172  
IC-Socket Series 172



IC-Leiste Serie 186  
IC-Strip Series 186

<b>Series</b>	<b>Contacts*</b>	<b>DIP*</b>	<b>Sleeve Plating</b>	<b>Clip Plating*</b>
<b>172</b>	<b>14</b>	<b>3</b>	<b>50</b>	<b>00</b>
172 IC-Fassung IC-Socket	06/08/10/14/16/ 18/20/22/24/28 ==> 20/22/24/28====> 24/28/32/36/ 40/48/50 =====>	3 7,62mm 4 10,16mm 6 15,24mm	50 Verzinkt (Standard) Tin plated (Standard)	00 Vergoldet (Standard) Gold plated (Standard) 10 Vergoldet 0,25µm 0,25µm gold plated 30 Vergoldet 0,75µm 0,75µm gold plated
<b>Series</b>	<b>Contacts*</b>	<b>DIP</b>	<b>Sleeve Plating</b>	<b>Clip Plating*</b>
<b>186</b>	<b>14</b>	<b>1</b>	<b>50</b>	<b>00</b>
186 IC-Leiste IC-Strip	01-64 Einreihig Single row	1 Einreihig Single row	50 Verzinkt (Standard) Tin plated (Standard)	(siehe oben) (see above)

\* Dies ist ein **Bestellbeispiel** -  
bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** -  
please replace by your specifications.

# Informationen zum Reflow-Lötverfahren

## Reflow Soldering Information

### Reflow-Lötempfehlung

#### Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150°C
Temperatur Maximum $T_{Smax}$	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich $T_L$	217°C
Verweildauer oberhalb $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur $T_P$	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur $T_P$	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150°C
Maximum Temperatur $T_{Smax}$	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature $T_L$	217°C
Duration above $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature $T_P$	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. $T_P$	Max. 8min

